


| SYMBOL | MIN | NOM | MAX |
|------------|---------|------|------|
| A | 1.35 | 1.50 | 1.65 |
| A1 | 0.05 | 0.10 | 0.15 |
| A2 | 1.35 | 1.40 | 1.50 |
| A3 | 0.50 | 0.60 | 0.7 |
| b | 0.38 | — | 0.50 |
| D | 4.80 | 4.90 | 5.00 |
| D1 | 3.2 | 3.3 | 3.4 |
| e | 1.27BSC | | |
| E | 5.80 | 6.00 | 6.20 |
| E1 | 3.80 | 3.90 | 4.00 |
| E2 | 2.3 | 2.4 | 2.5 |
| L | 0.45 | 0.60 | 0.80 |
| L1 | 1.04REF | | |
| L2 | 0.25BSC | | |
| R | 0.07 | — | — |
| R1 | 0.07 | — | — |
| h | 0.30 | 0.40 | 0.50 |
| θ | 0° | — | 8° |
| $\theta 1$ | 10° | 12° | 14° |
| $\theta 2$ | 8° | 10° | 12° |
| $\theta 3$ | 10° | 12° | 14° |
| $\theta 4$ | 8° | 10° | 12° |

NOTES:
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-137E
 2. DIMENSION D DOES NOT INCLUDE MOLD FLASH
 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH
 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.

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|  上海季丰电子科技有限公司 GIGA FORCE ELECTRONICS CO., Limited | | | |
| 制图 | 王磊 | Title | Package Outline ESOP8 |
| 核准 | 何桂港 | POD No | POD-SHJF-36 |
| 日期 | 2022. 3. 31 | DIMENSIONS IN: | mm Rev: A |